

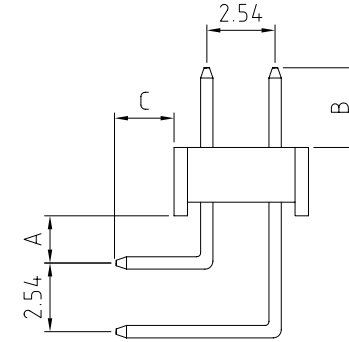
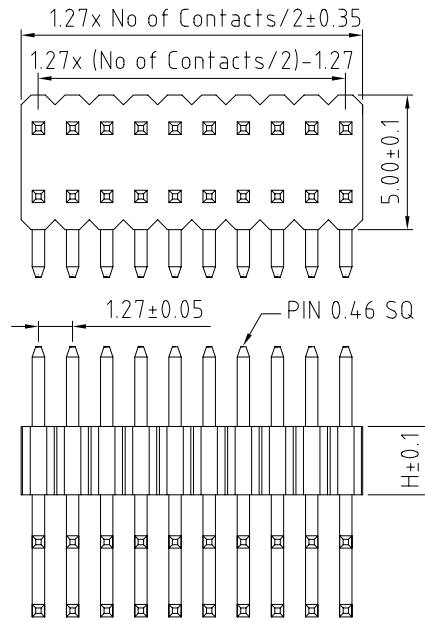
BB02-DE :- 1.27 x 2.54 PIN HEADER, DUAL ROW, RIGHT ANGLE, THROUGH HOLE, 06 TO 80 CONTACTS

SPECIFICATIONS

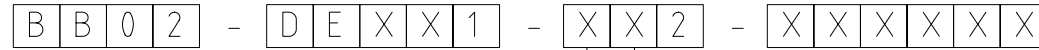
CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
OPERATING TEMPERATURE	-40° TO +105°C
CONTACT MATERIAL	COPPER ALLOY
INSULATOR MATERIAL	POLYESTER UL 94V-0
FINISH	STANDARD NYLON 6T
	GOLD, TIN, OR SELECTIVE PLATED
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC
	WAVE: 230°C FOR 5-10 SEC
	MANNUAL SOLDER: 350°C FOR 3-5 SEC

PACKED IN TRAY.

MATES WITH :-
 BB02-EA
 BB02-EB
 BB02-EC



HOW TO ORDER



NO. OF CONTACTS
 06 TO 80

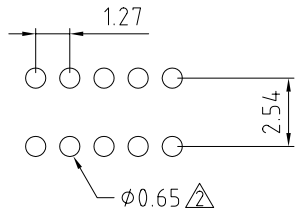
CONTACT PLATING
 GOLD FLASH = K
 10 MICRO INCHES GOLD = A
 15 MICRO INCHES GOLD = B
 30 MICRO INCHES GOLD = C
 TIN = T
 SELECTIVE GOLD FLASH = D
 SELECTIVE 10 MICRO INCHES GOLD = E
 SELECTIVE 15 MICRO INCHES GOLD = F
 SELECTIVE 30 MICRO INCHES GOLD = G
 STANDARD = K

HEIGHT 'H'
 1.70MM = A
 2.54MM = B
 3.00MM = C
 STANDARD = B

PIN LENGTH A (1/10mm)
 PLEASE SPECIFY PIN LENGTH REQUIRED
 I.E. 2.5mm = 25
 TOL. ±0.2mm

PIN LENGTH B (1/10mm)
 PLEASE SPECIFY PIN LENGTH REQUIRED
 I.E. 2.5mm = 25
 TOL. ±0.2mm

PIN LENGTH C (1/10mm)
 PLEASE SPECIFY PIN LENGTH REQUIRED
 I.E. 2.5mm = 25
 TOL. ±0.2mm



RECOMMENDED PC BOARD HOLE LAYOUT

REV. DATE & DRN 10 25/06/03 - NJR RELEASE 11 12/02/05 - NYW DRAWING MODIFICATION 12 19/09/05 - NYW AMEND PIN DIAMETER, AMEND PACKAGE AMEND PACKAGING 13 21/07/06 - NYW DRAWING MODIFICATION	Scale: 5:1	THIRD ANGLE	Unstated Tolerances: 0 Dec Places 1 Dec Places 2 Dec Places 3 Dec Places	Material SEE NOTE	 www.gradconn.com THIS DRAWING IS CONFIDENTIAL AND MUST NOT BE COPIED OR DISCLOSED WITHOUT WRITTEN CONSENT	Type: BB02-DE
	Drawn: NJR					Sheet 1 of 1
	App'd: XXXX	Title: PIN HEADER	NOT TO SCALE			Drawing Number:
	Date: 24 JUL '06	Revision: 13	UNIT: mm			BB02-DE Drawing E and O E